

**AMENDMENTS TO THE CLAIMS:**

The following listing of claims replaces all prior listings of claims in the present application.

**What Is Claimed Is:**

**1. (currently amended)** A temperature-compensated crystal oscillator comprising:

a substrate having a circuit pattern disposed on a surface thereof and mounting electrodes disposed on a reverse side thereof and electrically connected to said circuit pattern;

circuit components mounted on the surface of said substrate and electrically connected to said circuit pattern; and

a surface-mount crystal unit having a hermetically sealed crystal unit blank, and mounted on the surface of said substrate and electrically connected to said circuit pattern;

said crystal unit blank having a cavity defined in a mounting surface thereof, at least one of said circuit components being housed in said cavity and at least one of the remaining circuit components is disposed outside of said cavity.

**2. (original)** The temperature-compensated crystal oscillator according to claim 1, further comprising a temperature-compensating circuit, said temperature-compensating circuit comprising circuit components housed in said cavity.

**3. (original)** The temperature-compensated crystal oscillator according claim 2, wherein said temperature-compensated circuit is directly connected to said crystal unit, whereby the

temperature-compensated crystal oscillator serves as a temperature-compensated crystal oscillator of the direct compensation type.

**4. (original)** The temperature-compensated crystal oscillator according to claim 2, further comprising an adjusting capacitor for equalizing an oscillation frequency at a predetermined temperature to a target frequency, said adjusting capacitor being mounted on the surface of said substrate and disposed outside of said cavity.

**5. (original)** The temperature-compensated crystal oscillator according to claim 1, wherein said circuit components which are disposed in said cavity comprise chip-type circuit components each having a size of 0.6mm x 0.3mm.

**6. (original)** The temperature-compensated crystal oscillator according to claim 2, further comprising a variable capacitance diode for changing an oscillation frequency depending on a control voltage supplied from an external circuit, said variable capacitance diode being mounted on the surface of said substrate and disposed outside of said cavity.

**7. (new)** The temperature-compensated crystal oscillator according to claim 2, wherein the temperature-compensating circuit is formed as a chip-type circuit component.